



## How to test bonds » external sources » semiconductor alliances

- Automotive Industry Action Group
- DVS Certification Group Germany
- ERNI Connectors and Connector Systems
- Electrostatic Discharge Association
- Association Connecting Electronics Industries
- Semiconductor engineering standardization body of the Electronic Industries Alliance
- Semiconductor Equipment and Materials International
- Surface Mount Technology Association

## How to test bonds?

- Cold Bump Pull (CBP)
- Tweezer Pull (WP)
- Wire Pull (WP)

## External sources

- General
- Semiconductor alliances
- Semiconductor engineering
- Process control
- Articles and papers

This information can also be found at [www.qualitycontrol.how](http://www.qualitycontrol.how)

### **XYZTEC Netherlands**

J.F. Kennedylaan 14-B  
5981 XC Panningen  
Netherlands ([map](#) / [route](#))  
Tel: +31-77-3060920  
Fax: +31-77-3060919  
[sales@xyztec.com](mailto:sales@xyztec.com)  
[support@xyztec.com](mailto:support@xyztec.com)

### **Other offices**

- Germany  
- Taiwan  
- Thailand  
- United Kingdom  
- USA: California  
- USA: Massachusetts  
- [Distributors](#)

### **Bond testers**

- Condor *Sigma*  
- Condor *Sigma Lite*  
- Condor *Sigma W12*  
- Condor *150HF*

This is page 1/1  
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